



Contactless Module

Reliable electronic connection between the chip and the antenna for contactless cards

The Linxens Contactless Module (NOA3S / NOA3ST / NOA6XT) is suitable for connection to an antenna inlay when integrated into a contactless card that needs the highest reliability. Available for the Financial Services, Government, Transport and Access Control markets, the module is compliant with ISO standards and includes a contactless chip.

- Modules are based on Linxens internal stamped copper with cost effective selective silver plating
- Open tool designs are available in three different total module thicknesses, with the NOA6XT producing the thinnest module size of 250 µm.
- Delivered in standard 35 mm reel allowing card manufacturers to reuse the existing antenna inlay connection equipment for card production.

Product type	Preferred die thickness (µm)	Maximum die size (X x Y) (mm)	Maximum module height (µm)	nominal encapsulation X/Y size (mm)
Tape type				
NOA3S	150	2.8 x 3.1	380	4.80 x 5.10
NOA3ST	100	2.8 x 3.1	330	4.80 x 5.10
NOA6XT	50	2.8 x 3.1	250	4.80 x 5.10

- Linxens' proprietary stamping, plating and molding technology allows customize product design of leadframes and module that can be used for other applications based on customer demand.

Feel free to contact Linxens for any requests for tailored-made solutions to meet specific requirements.



SPECIALTY



Module Configurations

Material

- Material n° DIN EN CW452K
- Alloy CuSn6
- Hardness HV 180-230
- Thickness 0.06 mm / 0.08 mm
- Plating Ni: Min 1 µm
- Plating Ag: Min 1.5 µm in selective plating area

Packaging Material

- Ultrasonic ball wedge bonding
- Gold wire 23 µm, >99,9 %
- Black epoxy Based filled mold compound

Specifications

- Reel-to-reel format
- 35 mm film
- Pitch 9.5 mm

International Standards

- ISO/IEC 7810
- ISO/IEC 7816-1
- ISO/IEC 10373-1 and 10373-3
- MIL Std 883

Application Area

- Contactless chip card
- Government
- Transport
- Access control